

# HSB-800I

AMD LX-800/CS5536 ISA Half-Size SBC

## Thermal Image Analysis Report

Report NO: 08I080004

Release Date: Apr 02 2008

2008/04/02

Issue Stamp

Wenyuan Yang

Manager

Eva Yeh

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# Thermal Image Analysis

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I . Model Name: HSB-800I A1.0

II . Description: AMD LX-800/CS5536 ISA Half-Size SBC

III . Date: Apr 02 2008

IV. Measure Site: AAEON QE Dept.

V. Issued by : Eva Yeh

VI. Equipment:

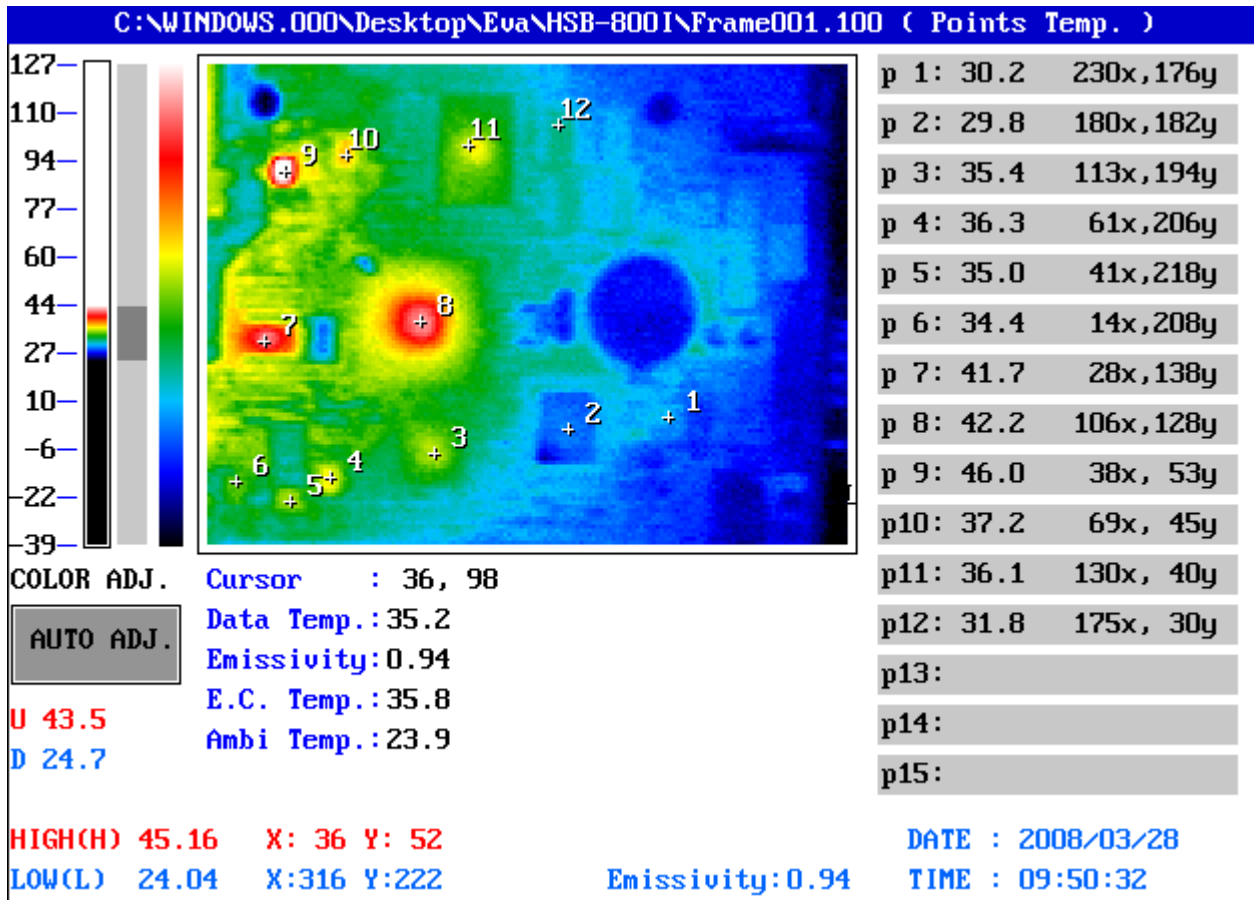
TVS-100 series by NIPPON AVIONICS CO., LTD.

VII. Simulation Environment:

- Temperature: Component Side-1 : 23.9°C , Component Side-2 : 24.2°C , Component Side-3 : 24.8°C , Component Side-4 : 25.0°C
- CPU : AMD LX-800 500 MHz
- RAM : On Board 128MB DDR400(ESMT M13S2561616A-5T)
- BIOS : HSB-800I BIOS Rev 1.1 (03/25/2008)
- CF Card : N/A
- HDD : WD800JB-00JJC0 80GB
- Application Software: Run Prime95 under Windows XP Professional V2002 Service Pack 2
- Take Picture Time: After Power on 2 hours.

## Temperature Profile Test:

### Component Side-1:

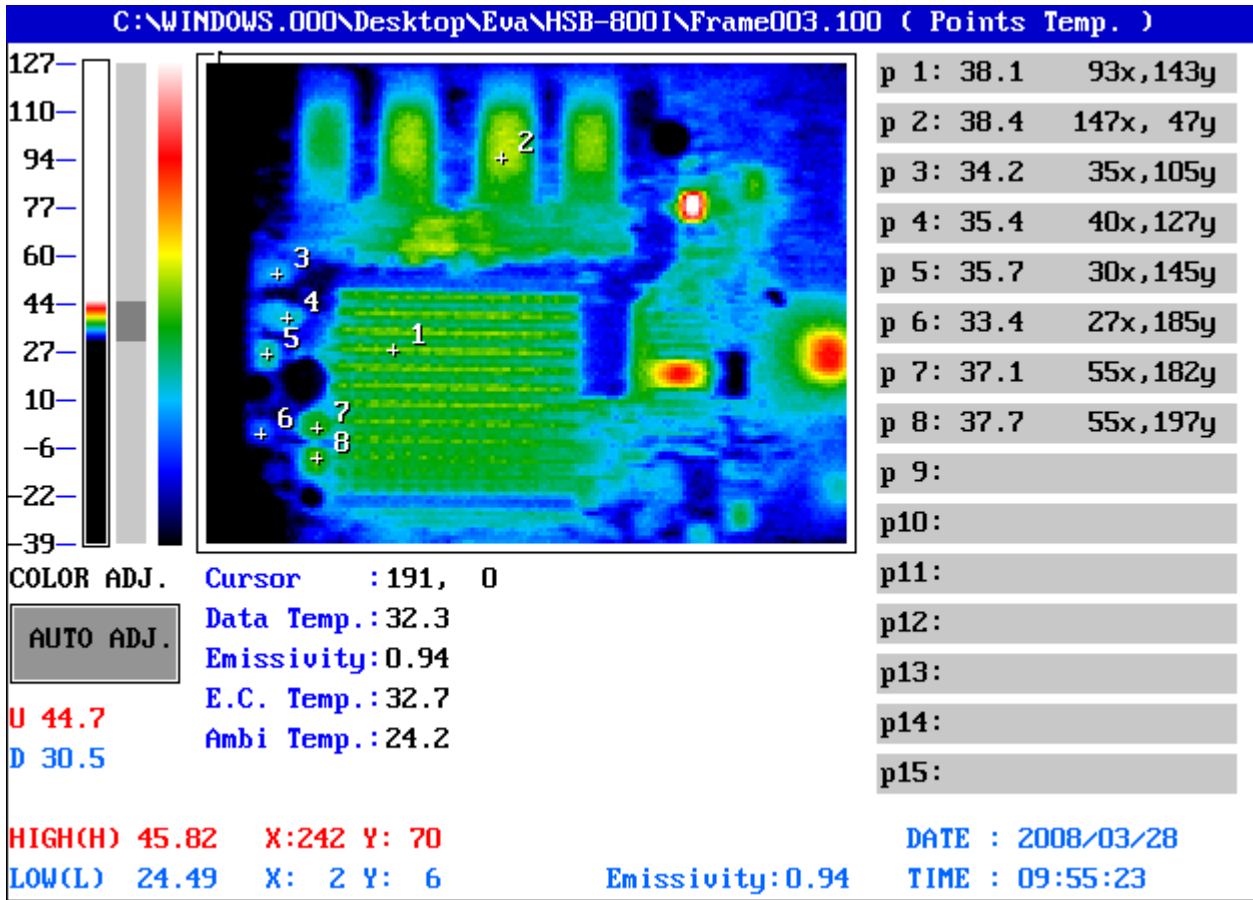


Point	Position	Describe	Tc (°C)	Tm (23.9°C)	Tm (60°C)	Note
1	U24	(TF)IC.SMD.SOIC 8P.2.5V 1K bits.Microchip. 93LC46B/SN;EE-A990454;14S6334610;TWN	155	30.2	66.3	
2	U25	AAEON/(TF)Flash PLCC BIOS.1024K.CS:4C55h.HSB-800I.Rev 1.0.;EE-A080091;14S62800I0;TWN	N/A	29.8	65.9	
3	U27	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip. ITE.IT8888G-L;EE-A051091;14S4888801;TWN	70	35.4	71.5	
4	U28	(TF)IC.SMD SOP.8Pin Switching PWM Controller. IR.IRU3037CSPbF;EE-A020732;14S2303700;TWN	125	36.3	72.4	
5	U30	(TF)Dual N-Channel.SMD SO-8.2.5V MOSFET.APEC.AP9926GM;EE-A030055;1315992601;TWN	125	35.0	71.1	
6	U29	(TF)PWR.SMD SO-8.P-Channel 2.5V(G-S) MOSFET. VISHAY.SI9933BDY-T1-E3;EE-A041262;1315993311;TWN	125	34.4	70.5	
7	U19	(TF)IC.SMD.SSOP28.Clock Generator. ICS.MK1491-09FLN;EE-A051233;14S3149103;TWN	100	41.7	77.8	

8	U17	(TF)IC.SMD 208PBGA.I/O Companion.Multi-Function South Bridge.AMD.CS5536AD;EE-A061313;14S4553600;TWN	110	42.2	78.3	
9	U11	(TF)IC.SMD SO8.3A Linear Regulator. Anpec.APL5331KC-TRL;EE-A041712;14S2533100;TWN	125	46.0	82.1	
10	U9	(TF)IC.SMD SO-8.1.5A.Low Dropout Regulator.Adj(1.2~4.8V). SEMTECH.SC1565IS-TRT;EE-A031087;14S3156500;TWN	125	37.2	73.3	
11	U8	(TF)IC.SMD.QFP128P Super I/O. ITE.IT8712F/KX-L;EE-A061481;14S4871204;TWN	100	36.1	72.2	
12	U5	(TF)IC.SMD.SSOP 28P.RS232 Driver ESD 15KV. ZYWYN.ZT213LEEA;EE-A071674;14S4021305;TWN	85	31.8	67.9	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
2. Any Tm value showed in **red words** which meaning the value is over the Tc+ 5 degree C of this device specification

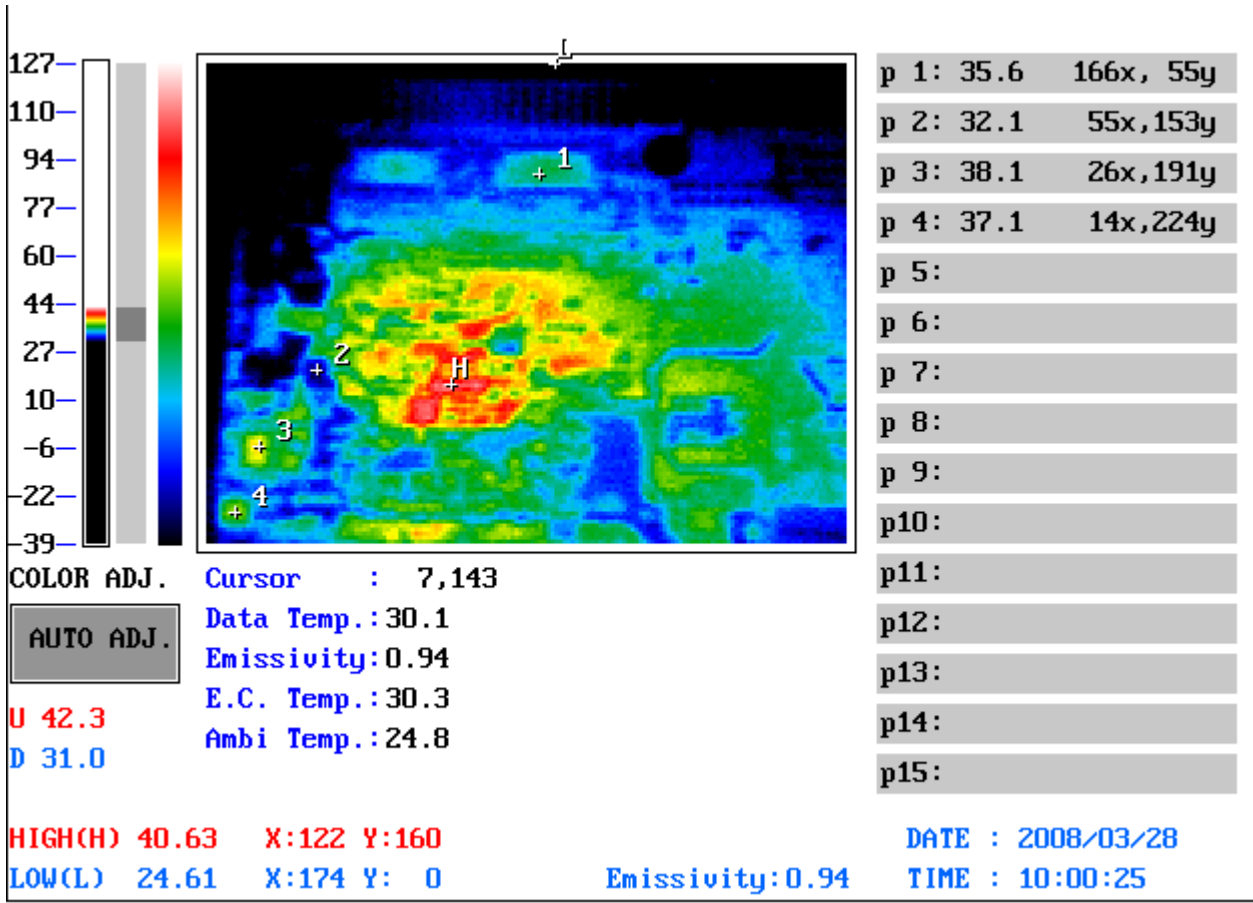
Component Side-2:



Point	Position	Describe	Tc (°C)	Tm (24.2 °C)	Tm (60°C)	Note
1	U20	(TF)AMD CPU.BGU481.LX-800.500MHZ.1.25V. AMD.ALXD800EEXJ2VD C3;EE-A080020;14S4800004;TWN	85	38.1	73.9	
2	U3	(TF)IC.SMD.SDRAM.16Mb*16.DDR400.TSOP-II 66P.2.5V. ESMT.M13S2561616A-5TG;EE-A071532;14S6861601;TWN	85	38.4	74.2	
3	C31	(TF)SP CAP.[8.2 μ F~470 μ F].[2V~8V].20%.SMD.Panasonic. EEF/ECG 系列 (耐溫 260°C);EE-A060158;118*****8*;TWN	105	34.2	70	
4	L1	(TF)COIL.4.7uH 2.5A.+20%.SMD.SMTDR54N-4R7M.震 元.430-02210;EE-A051286;1211104769;TWN	85	35.4	71.2	
5	U18	(TF)PWR.SMD.SOP8.Dual N MOSFET.30V.9.1A/6.8A. CET.CEM3138;EE-A051316;1315313800;TWN	125	35.7	71.5	
6	U22	(TF)PWR.SMD SO-8.P-Channel MOSFET. ANPEC.APM4463KC-TRL;EE-A041711;1315446310;TWN	125	33.4	69.2	
7	L2	(TF)COIL.4.7uH 2.5A.+20%.SMD.SMTDR54N-4R7M.震 元.430-02210;EE-A051286;1211104769;TWN	85	37.1	72.9	

8	U26	(TF)PWR.SMD.SOP8.Dual N MOSFET.30V.9.1A/6.8A. CET.CEM3138;EE-A051316;1315313800;TWN	125	37.7	73.5	
<p>1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C</p> <p>2. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification</p>						

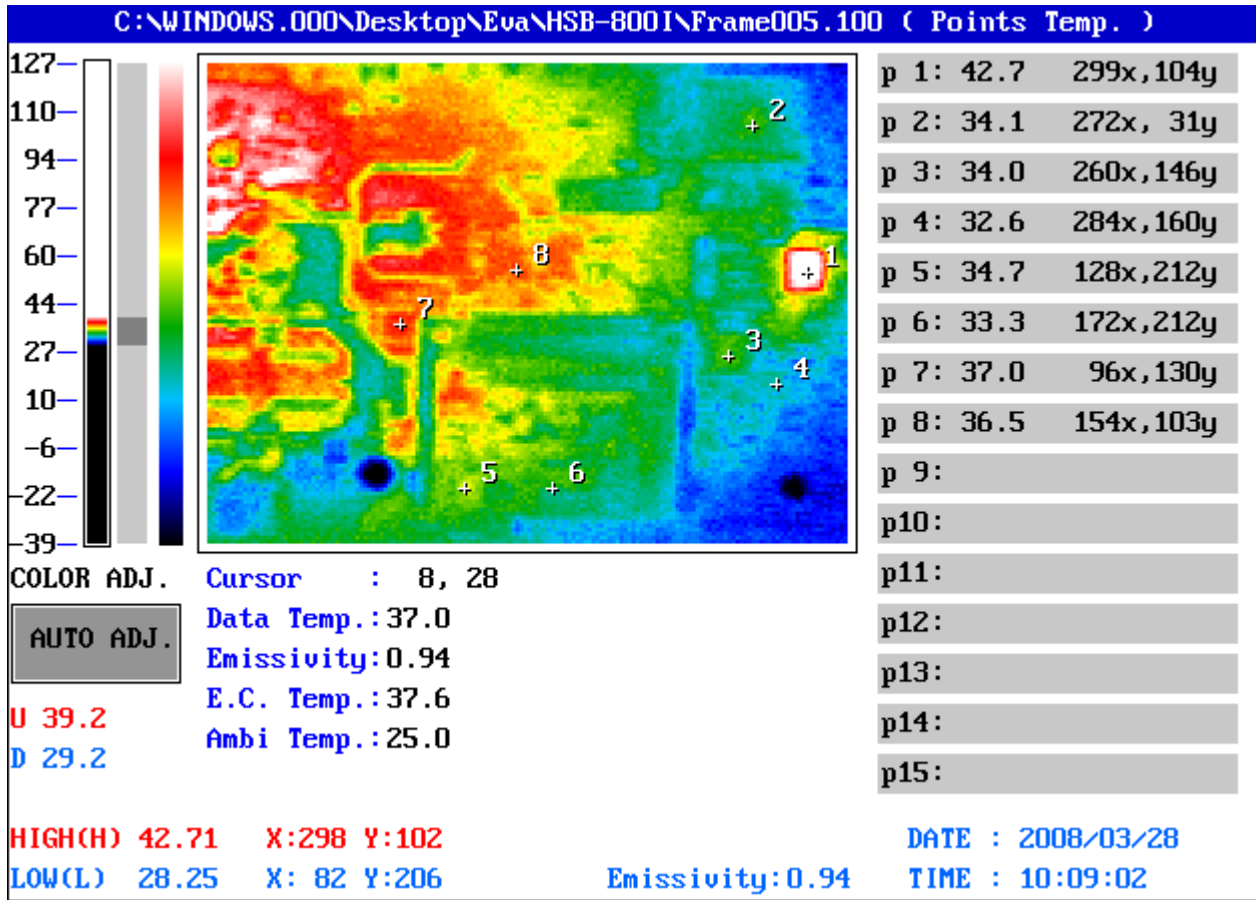
### Component Side-3:



Point	Position	Describe	Tc (°C)	Tm (24.8 °C)	Tm (60°C)	Note
1	U52	(TF)IC.SMD.TSSOP56.FlatLink Transmitter. TI.SN75LVDS83;EE-A051271;14S4758300;TWN	100	35.6	70.8	
2	U48	(TF)PWR.SMD SO-8.P-Channel MOSFET. ANPEC.APM4463KC-TRL;EE-A041711;1315446310;TWN	125	32.1	67.3	
3	U45	(TF)IC.SMD TSSOP14.Synchronous Buck Regulator. NS.LM2727;EE-A051265;14S2272700;TWN	100	38.1	73.3	
4	U42	(TF)IC.SMD TSSOP14.Synchronous Buck Regulator. NS.LM2727;EE-A051265;14S2272700;TWN	100	37.1	72.3	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C  
 2. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification

## Component Side-4:





Point	Position	Describe	Tc (°C)	Tm (25.0 °C)	Tm (60°C)	Note
1	U46	(TF)IC.SMD.2 Channel Audio Codec. Realtek.ALC203-LF;EE-A051262;14S3020300;TWN	100	42.7	77.7	
2	U49	(TF)IC.SMD QFP 128P.PCI Ethernet Chip 10/100BaseT. REALTEK.RTL8100C-LF;EE-A031177;14S4810001;TWN	70	34.1	69.1	
3	U41	(TF)IC.SMD.LQFP 48P.LPC to 4 UART. FINTEK.F81216DG;EE-A050807;14S4121601;TWN	70	34.0	69	
4	U40	(TF)IC.SMD SOIC 8P.Dual USB PowerControl Switch. MICREL.MIC2026-1YM;EE-A020283;14S2202600;TWN	115	32.6	67.6	
5	U32	(TF)IC.SMD.TSSOP 14P. PHILIPS.74HCT14PW;EE-A021239;14S5801402;TWN	115	34.7	69.7	
6	U34	(TF)IC.SMD.QSOP 28P.IEEE 1284 Termination Network. CMD.PACSZ1284-04QR;EE-A060352;14S3128421;TWN	85	33.3	68.3	
7	U43	(TF)IC.SO8 SMD.Voltage Detecting.System Resetting IC. MITSUBISHI.M51957A;EE-A060753;14S4195710;TWN	85	37.0	72	
8	C175	(TF)SP CAP.[8.2 μ F~470 μ F].[2V~8V].20%.SMD. Panasonic.EEF/ECG 系列(耐溫 260°C); EE-A060158;118****8*;TWN	105	36.5	71.5	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
2. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification